2SD1978

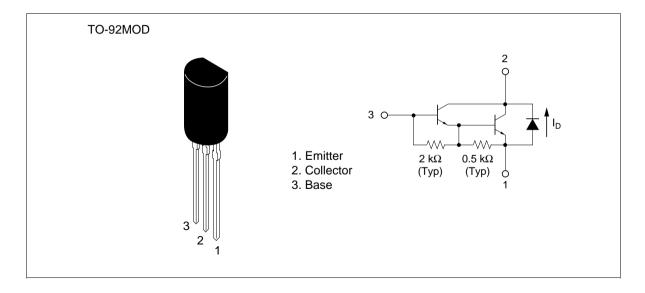
Silicon NPN Epitaxial, Darlington

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Application

- Low frequency power amplifier
- Complementary pair with 2SB1387

Outline





2SD1978

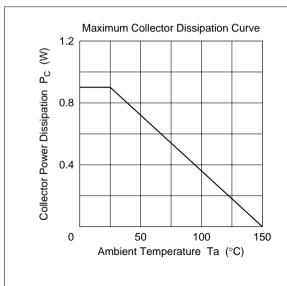
Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

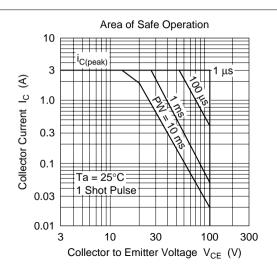
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	120	V
Collector to emitter voltage	V _{CEO}	120	V
Emitter to base voltage	V _{EBO}	7	V
Collector current	I _c	1.5	A
Collector peak current	ic (peak)	3.0	A
Collector power dissipation	P _c	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
E to C diode forward current	I _D	1.5	A

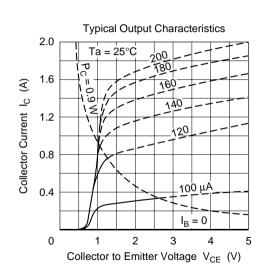
Electrical Characteristics ($Ta = 25^{\circ}C$)

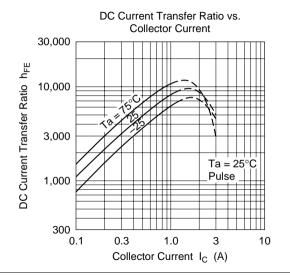
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	120	_	_	V	$I_{\rm C} = 0.1 \text{ mA}, I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	120	_	_	V	I_{C} = 10 mA, R_{BE} = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	_	_	V	$I_{\rm E} = 50 \text{ mA}, I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	1.0	μΑ	V _{CB} = 100 V, I _E = 0
	I _{CEO}	_	_	10	μΑ	$V_{CE} = 100 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	h_{FE}	2000	_	30000		$V_{CE} = 3 \text{ V}, I_{C} = 1 \text{ A}^{*1}$
Collector to emitter saturation voltage	V _{CE(sat)1}	_	_	1.5	V	I _C = 1 A, I _B = 1 mA* ¹
	V _{CE(sat)2}	_	_	2.0	V	$I_{\rm C}$ = 1.5 A, $I_{\rm B}$ = 1.5 mA* ¹
Base to emitter saturation voltage	$V_{BE(sat)1}$	_	_	2.0	V	$I_{C} = 1 \text{ A}, I_{B} = 1 \text{ mA}^{*1}$
	V _{BE(sat)2}	_	_	2.5	V	$I_{\rm C}$ = 1.5 A, $I_{\rm B}$ = 1.5 mA* ¹
E to C diode forward voltage	V _D	_	_	3.0	V	$I_D = 1.5 \text{ A}^{*1}$

Note: 1. Pulse test

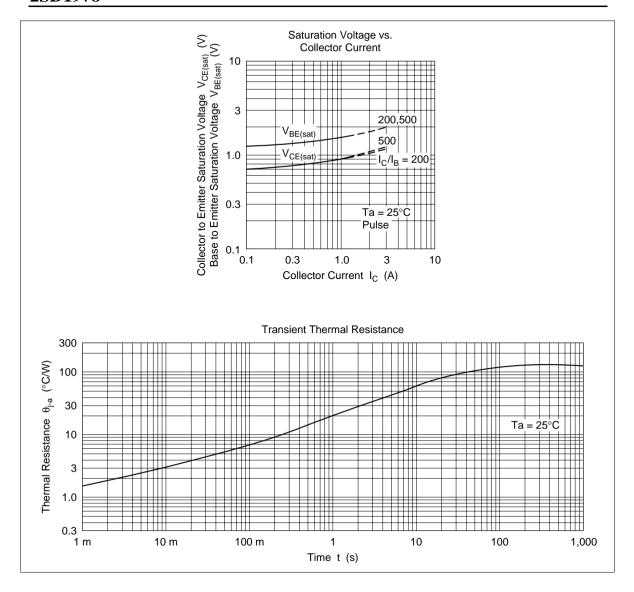




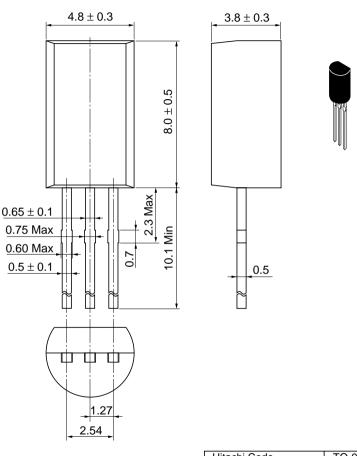




2SD1978



Unit: mm



Hitachi Code TO-92 Mod

JEDEC —

EIAJ Conforms

Weight (reference value) 0.35 g

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